US00D772736S

(12) United States Design Patent
Hu et al.

(10) **Patent No.: US D772,736 S**
(45) **Date of Patent: ** Nov. 29, 2016**

(54) **SENSOR MODULE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/524,294**

(22) Filed: **Apr. 20, 2015**

(51) **LOC (10) Cl.** **10-04**

(52) **U.S. Cl.**
USPC **D10/65**

(58) **Field of Classification Search**
USPC D10/46, 65, 70; D16/237
CPC G05D 1/0094; G05D 1/02; G05D 1/0202; G05D 1/0204; G03B 15/006; G03B 37/00; G03B 37/04; G01S 19/14; H04N 7/185; H04N 5/3692
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

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D754,007 S	*	4/2016	Stefancic, Sr.	D10/65

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(57) **CLAIM**

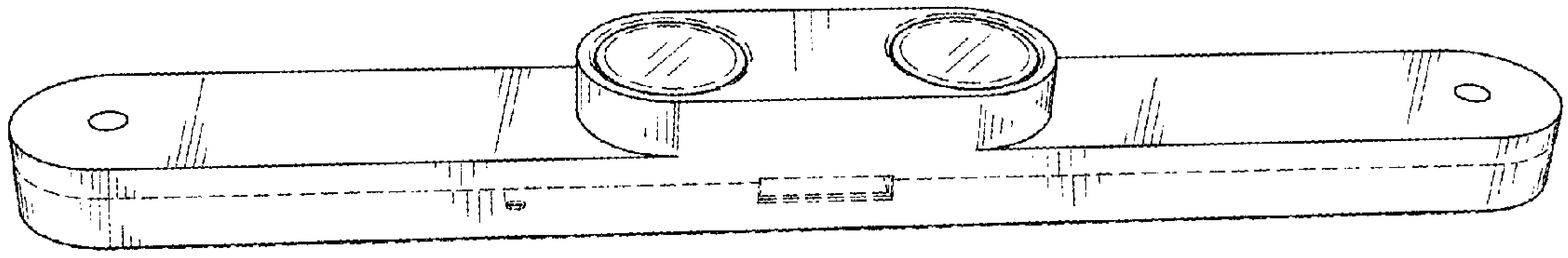
The ornamental design of a sensor module, as shown and described.

DESCRIPTION

FIG. **1** is perspective view of a sensor module showing the claimed design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left-side elevational view thereof;
FIG. **5** is a right-side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

Broken lines are for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



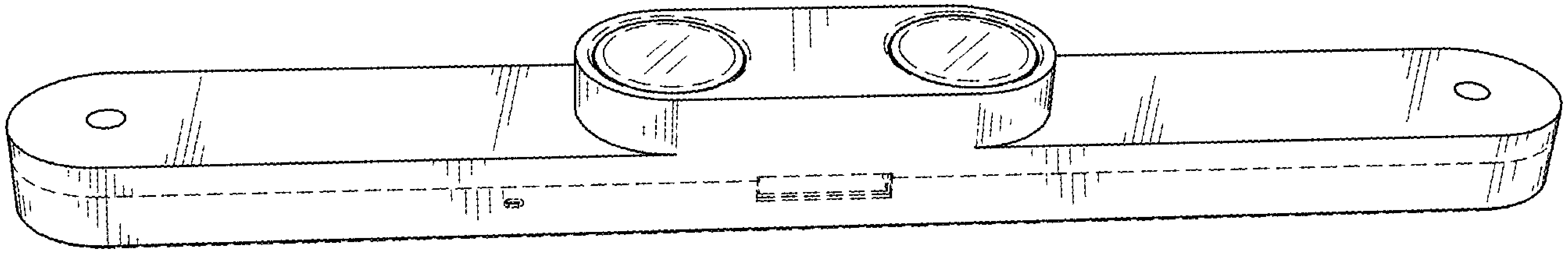


FIG. 1

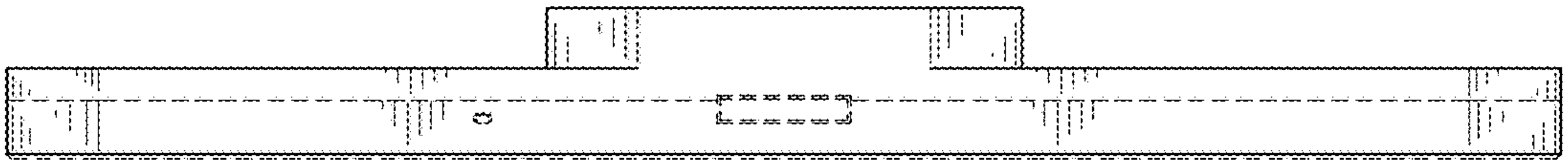


FIG. 2

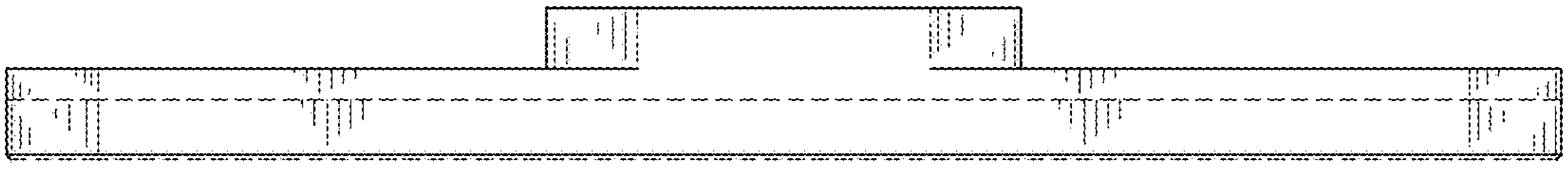


FIG. 3

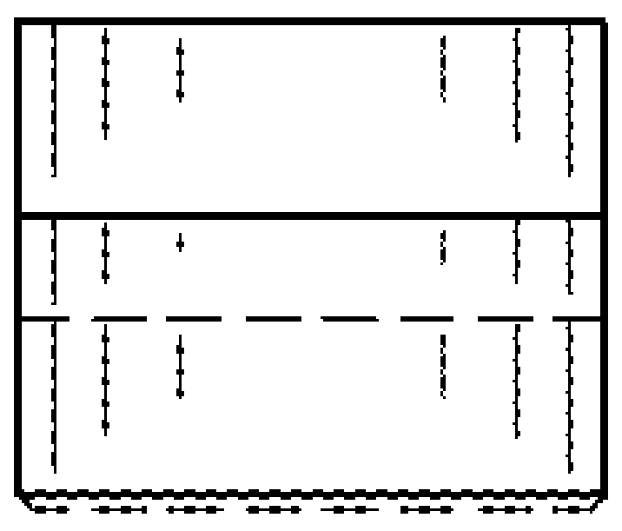


FIG. 4

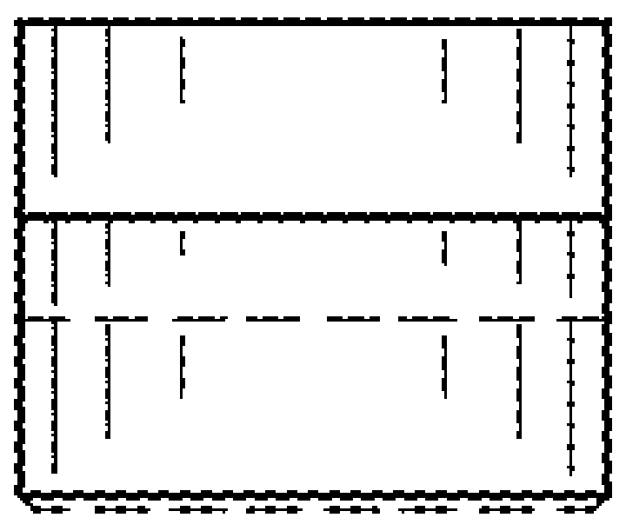


FIG. 5

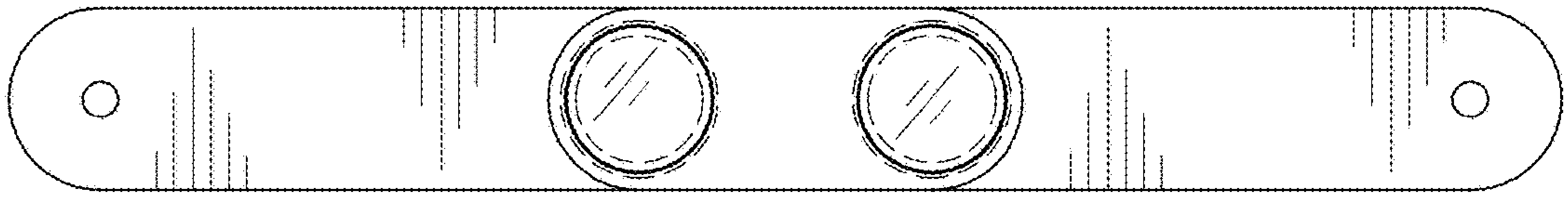


FIG. 6

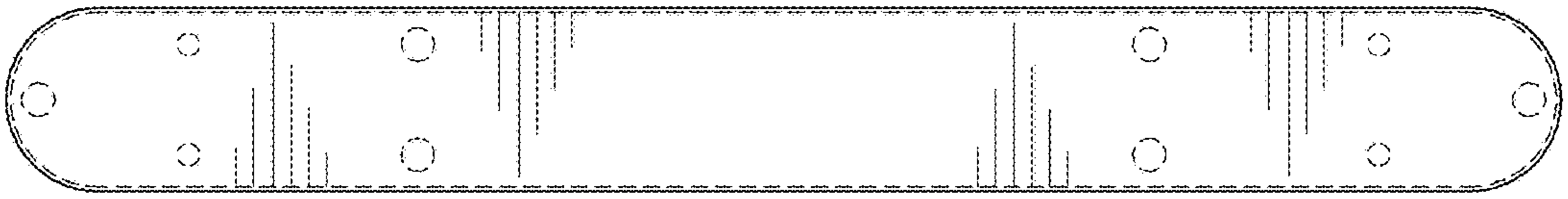


FIG. 7